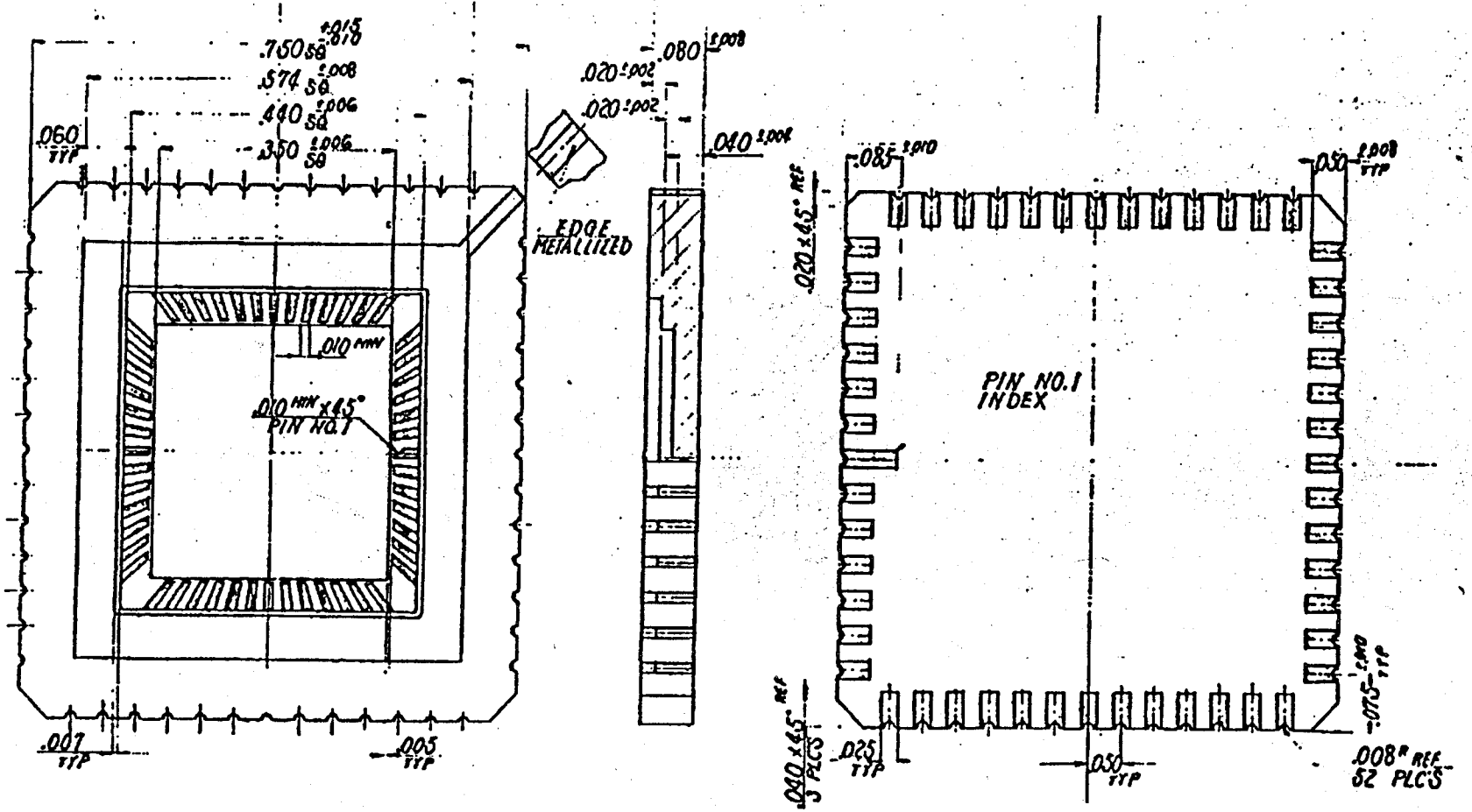

NOTE

1. ALL EXPOSED METALLIZED AREA SHALL BE GOLD PLATED 60 MICRO INCH MIN THICKNESS OVER NICKEL PLATED.
2. SEAL RING FLATNESS .003
3. SEAL RING AND DIE ATTACH PAD ARE NOT GROUND TO A LEAD.

A	ADD: SHEET NO. 2/2				
	CHANGE	DATE	DRAWN	CHECKED	APPROVED

NAME: 52 LEAD CHIP CARRIER
SCALE: 8/1
MATERIAL: KYOCERA A-440
TOLERANCES: ±1% NLT ±.005
KYOTO CERAMIC CO., LTD. KYOTO JAPAN
DRAWN / CHECKED / APPROVED
DATE: 79.4.10
S=0 D=0 HG-520
PB-92155-A